

RADIATION HARDENED N-CHANNEL MOSFET

Qualified per MIL-PRF-19500/603

DEVICES

2N7394 2N7394U

LEVELS

**MSR (100K RAD(Si))
 MSF (300K RAD(Si))
 SPACE Equivalents**

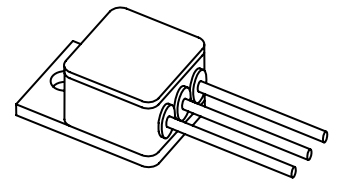
ABSOLUTE MAXIMUM RATINGS ($T_C = +25^\circ\text{C}$ unless otherwise noted)

| Parameters / Test Conditions | Symbol | Value | Unit |
|--|-------------------|----------------------|------------------|
| Drain – Source Voltage | V_{DS} | 60 | Vdc |
| Gate – Source Voltage | V_{GS} | ± 20 | Vdc |
| Continuous Drain Current $T_C = +25^\circ\text{C}$ | I_{D1} | 35.0 | A dc |
| Continuous Drain Current $T_C = +100^\circ\text{C}$ | I_{D2} | 30.0 | A dc |
| Max. Power Dissipation | P_{tl} | 150 ⁽¹⁾ | W |
| Drain to Source On State Resistance | $R_{ds(on)}$ | 0.027 ⁽²⁾ | Ω |
| Operating & Storage Temperature | T_{op}, T_{stg} | -55 to +150 | $^\circ\text{C}$ |

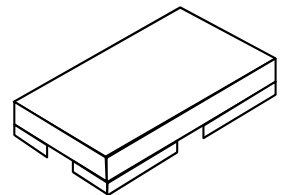
Note: (1) Derated Linearly by 1.2 W/ $^\circ\text{C}$ for $T_C > +25^\circ\text{C}$
 (2) $V_{GS} = 12\text{Vdc}$, $I_D = 30.0\text{A}$

PRE-IRRADIATION ELECTRICAL CHARACTERISTICS ($T_A = +25^\circ\text{C}$, unless otherwise noted)

| Parameters / Test Conditions | Symbol | Min. | Max. | Unit |
|--|---|------------|-------------------------|------------------------------------|
| OFF CHARACTERISTICS | | | | |
| Drain-Source Breakdown Voltage $V_{GS} = 0\text{V}$, $I_D = 1\text{mA dc}$ | $V_{(BR)DSS}$ | 60 | | Vdc |
| Gate-Source Voltage (Threshold) $V_{DS} \geq V_{GS}$, $I_D = 1.0\text{mA}$ $V_{DS} \geq V_{GS}$, $I_D = 1.0\text{mA}$, $T_j = +125^\circ\text{C}$ $V_{DS} \geq V_{GS}$, $I_D = 1.0\text{mA}$, $T_j = -55^\circ\text{C}$ | $V_{GS(th)1}$ $V_{GS(th)2}$ $V_{GS(th)3}$ | 2.0 1.0 | 4.0 5.0 | Vdc |
| Gate Current $V_{GS} = \pm 20\text{V}$, $V_{DS} = 0\text{V}$ $V_{GS} = \pm 20\text{V}$, $V_{DS} = 0\text{V}$, $T_j = +125^\circ\text{C}$ | I_{GSS1} I_{GSS2} | | ± 100 ± 200 | nA dc |
| Drain Current $V_{GS} = 0\text{V}$, $V_{DS} = 48\text{V}$ $V_{GS} = 0\text{V}$, $V_{DS} = 60\text{V}$, $T_j = +125^\circ\text{C}$ $V_{GS} = 0\text{V}$, $V_{DS} = 48\text{V}$, $T_j = +125^\circ\text{C}$ | I_{DSS1} I_{DSS2} I_{DSS3} | | 25 1.0 0.25 | $\mu\text{A dc}$ mA dc mA dc |
| Static Drain-Source On-State Resistance $V_{GS} = 12\text{V}$, $I_D = 30.0\text{A}$ pulsed $V_{GS} = 12\text{V}$, $I_D = 35.0\text{A}$ pulsed $T_j = +125^\circ\text{C}$ $V_{GS} = 12\text{V}$, $I_D = 30.0\text{A}$ pulsed | $r_{DS(on)1}$ $r_{DS(on)2}$ $r_{DS(on)3}$ | | 0.027 0.030 0.060 | Ω Ω Ω |
| Diode Forward Voltage $V_{GS} = 0\text{V}$, $I_D = 35.0\text{A}$ pulsed | V_{SD} | | 1.4 | Vdc |



**TO-254AA
 MSR2N7394, MSF2N7394
 See Figure 1**



**U-PKG (SMD-1)
 (TO-267AB)
 MSR2N7394U, MSF2N7394U
 See Figure 2**

DYNAMIC CHARACTERISTICS

| Parameters / Test Conditions | Symbol | Min. | Max. | Unit |
|---|-------------------------------------|---|-----------------|------|
| Gate Charge: On-State Gate Charge Gate to Source Charge Gate to Drain Charge | $Q_{g(on)}$ Q_{gs} Q_{gd} | | 200 60 75 | nC |
| | | $V_{GS} = 12V, I_D = 35.0A$ $V_{DS} = 30V$ | | |

SWITCHING CHARACTERISTICS

| Parameters / Test Conditions | Symbol | Min. | Max. | Unit |
|---|---|---|-----------------------|------|
| Switching time tests: Turn-on delay time Rinse time Turn-off delay time Fall time | $t_{d(on)}$ t_r $t_{d(off)}$ t_f | | 27 100 75 75 | ns |
| | | $I_D = 35.0A, V_{GS} = 12Vdc,$ Gate drive impedance = $2.35\Omega,$ $V_{DD} = 50Vdc$ | | |
| Diode Reverse Recovery Time | t_{rr} | | 280 | ns |
| | | $di/dt \leq 100A/\mu s, V_{DD} \leq 30V,$ $I_F = 35.0A$ | | |

POST-IRRADIATION ELECTRICAL CHARACTERISTICS (3) ($T_A = +25^\circ C$, unless otherwise noted)

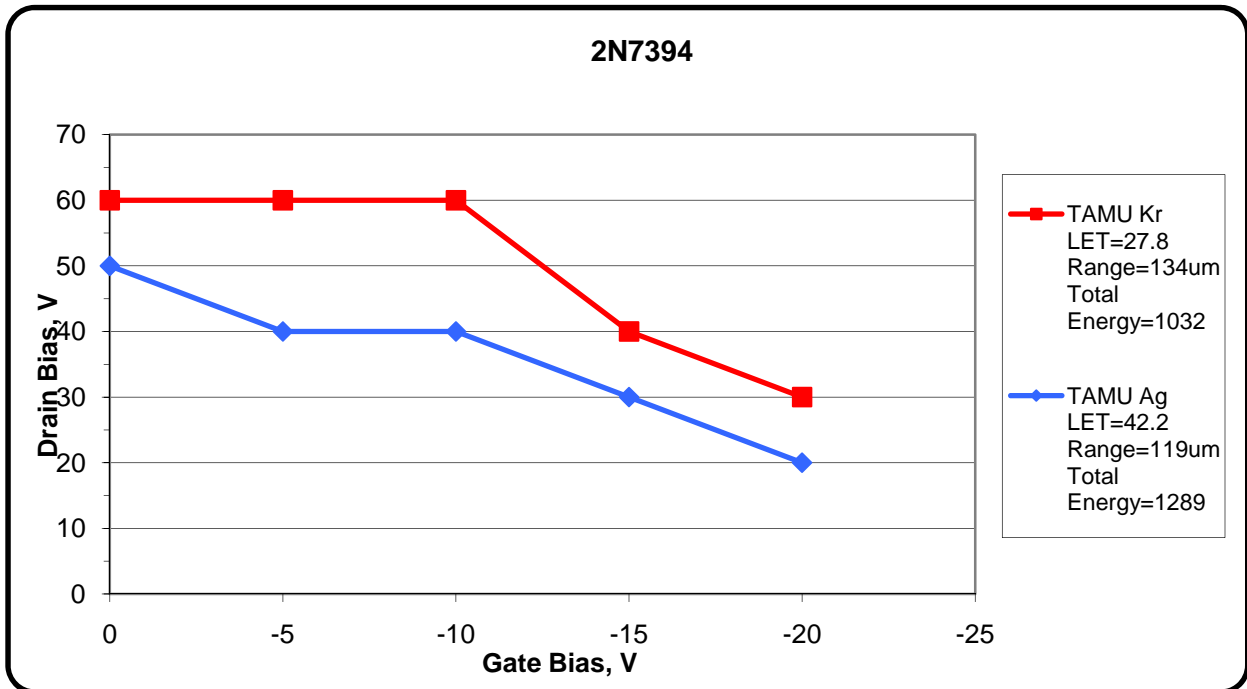
| Parameters / Test Conditions | Symbol | Min. | Max. | Unit |
|--|--------------------------------|-------------|-------------|-----------|
| Drain-Source Breakdown Voltage $V_{GS} = 0V, I_D = 1mA$ | $V_{(BR)DSS}$ | 60 | | Vdc |
| Gate-Source Voltage (Threshold) $V_{DS} \geq V_{GS}, I_D = 1.0mA$ MSR $V_{DS} \geq V_{GS}, I_D = 1.0mA$ MSF | $V_{GS(th)1}$ $V_{GS(th)1}$ | 2.0 1.25 | 4.0 4.5 | Vdc |
| Gate Current $V_{GS} = \pm 20V, V_{DS} = 0V$ | I_{GSS1} | | ± 100 | nAdc |
| Drain Current $V_{GS} = 0V, V_{DS} = 48V$ MSR $V_{GS} = 0V, V_{DS} = 48V$ MSF | I_{DSS1} | | 25 50 | μ Adc |
| Static Drain-Source On-State Voltage $V_{GS} = 12V, I_D = 30.0A$ pulsed MSR $V_{GS} = 12V, I_D = 30.0A$ pulsed MSF | $V_{DS(on)}$ | | 0.81 1.2 | Vdc |
| Diode Forward Voltage $V_{GS} = 0V, I_D = 35.0A$ pulsed | V_{SD} | | 1.4 | Vdc |

NOTE:

- (3) Post-Irradiation Electrical Characteristics apply to devices subjected to Steady State Total Dose Irradiation testing in accordance with MIL-STD-750 Method 1019. Separate samples are tested for VGS bias (12V), and VDS bias (80V) conditions.

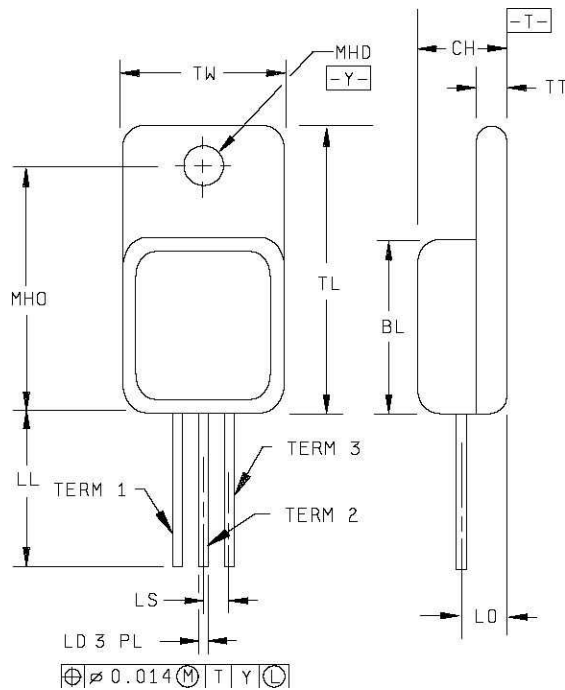
Single Event Effect (SEE) Characteristics:

Heavy Ion testing of the 2N7394 has been characterized at the Texas A&M cyclotron. The following SOA curve has been established using the elements, LET, range, and Total Energy conditions as shown:



It should be noted that total energy levels are considered to be a factor in SEE characterization. Comparisons to other datasets should not be based on LET alone. Please consult factory for more information.

PACKAGE DIMENSIONS

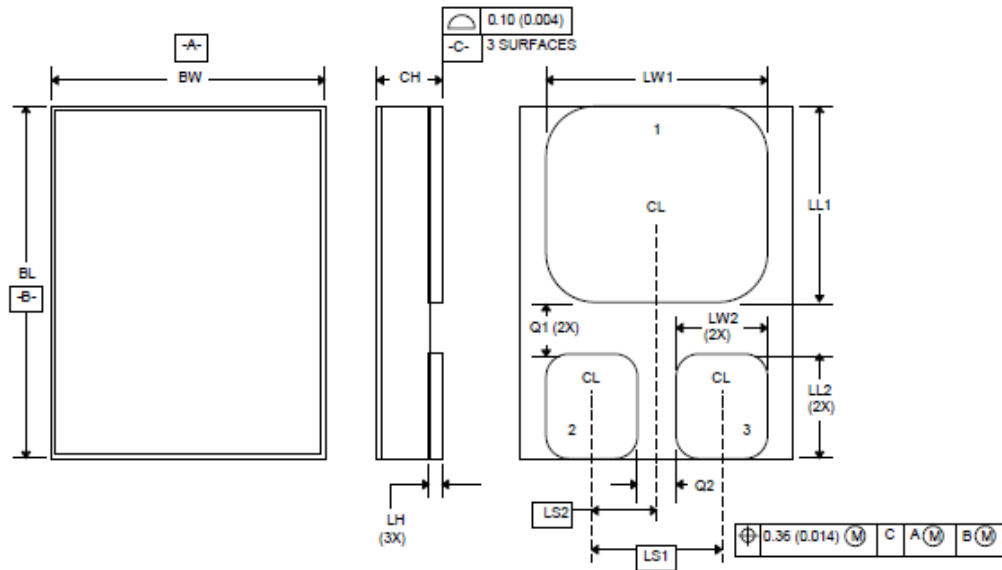


| Symbol | Dimensions | | | |
|--------|------------|------|-------------|-------|
| | Inches | | Millimeters | |
| | Min | Max | Min | Max |
| BL | .535 | .545 | 13.59 | 13.84 |
| CH | .249 | .260 | 6.32 | 6.60 |
| LD | .035 | .045 | 0.89 | 1.14 |
| LL | .510 | .570 | 12.95 | 14.48 |
| LO | .150 BSC | | 3.81 BSC | |
| LS | .150 BSC | | 3.81 BSC | |
| MHD | .139 | .149 | 3.53 | 3.78 |
| MHO | .665 | .685 | 16.89 | 17.40 |
| TL | .790 | .800 | 20.07 | 20.32 |
| TT | .040 | .050 | 1.02 | 1.27 |
| TW | .535 | .545 | 13.59 | 13.84 |
| Term 1 | Drain | | | |
| Term 2 | Source | | | |
| Term 3 | Gate | | | |

NOTES:

1. Dimensions are in inches.
2. Millimeters are given for general information only.
3. Refer to applicable symbol list.
4. In accordance with ASME Y14.5M, diameters are equivalent to ϕx symbology.
5. All terminals are isolated from case.

FIGURE 1. Physical dimensions for TO-254AA (2N7268, 2N7269, 2N7270, and 2N7394).



NOTES:

1. Dimensions are in inches.
2. Millimeters are given for general information only.
3. The lid shall be electrically isolated from the drain, gate and source.
4. In accordance with ASME Y14.5M, diameters are equivalent to ϕ x symbology.

| Symbol | Dimensions | | | |
|-----------------|------------|------|-------------|-------|
| | SMD-1 | | | |
| | Inches | | Millimeters | |
| | Min | Max | Min | Max |
| BL | .620 | .630 | 15.75 | 16.00 |
| BW | .445 | .455 | 11.30 | 11.56 |
| CH | | .142 | | 3.60 |
| LH | .010 | .020 | 0.26 | 0.50 |
| LL ₁ | .410 | .420 | 10.41 | 10.67 |
| LL ₂ | .152 | .162 | 3.86 | 4.11 |
| LS ₁ | .210 BSC | | 5.33 BSC | |
| LS ₂ | .105 BSC | | 2.67 BSC | |
| LW ₁ | .370 | .380 | 9.40 | 9.65 |
| LW ₂ | .135 | .145 | 3.43 | 3.68 |
| Q ₁ | .030 | | 0.76 | |
| Q ₂ | .035 | | 0.89 | |
| Term 1 | Drain | | | |
| Term 2 | Gate | | | |
| Term 3 | Source | | | |

FIGURE 2. - Dimensions and configuration of surface mount package outline.
TO-276AC (2N7268U, 2N7269U, 2N7270U, AND 2N7394U)